

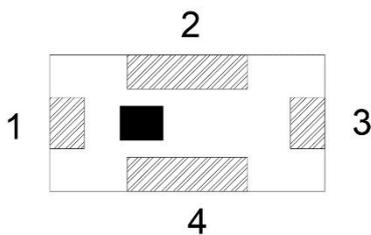
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

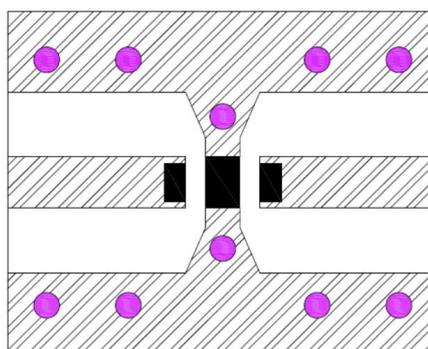
NO.	Parameter	Frequency (MHz)	SPC	
			Min.	Max.
1	Insertion Loss (dB)	2500~2700		2.2
2	VSWR	2500~2700		2.1
3	Attenuation (dB)	806~825	25	
		825~849	25	
		880~915	25	
		1710~1785	25	
		1850~1910	25	
		1920~1980	15	
		3300~3900	5	
4	In/Output Impedance (Ω)	50		

Construction



PIN	Connection
1	Input port
2	GND
3	Output port
4	GND

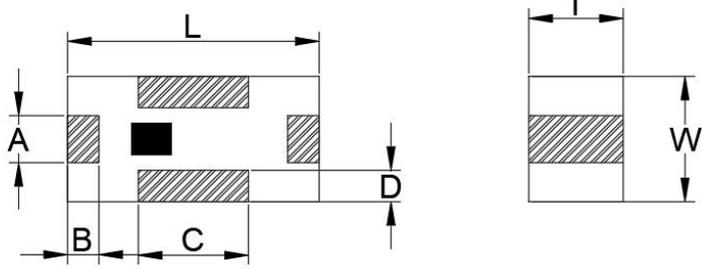
Mounting Considerations



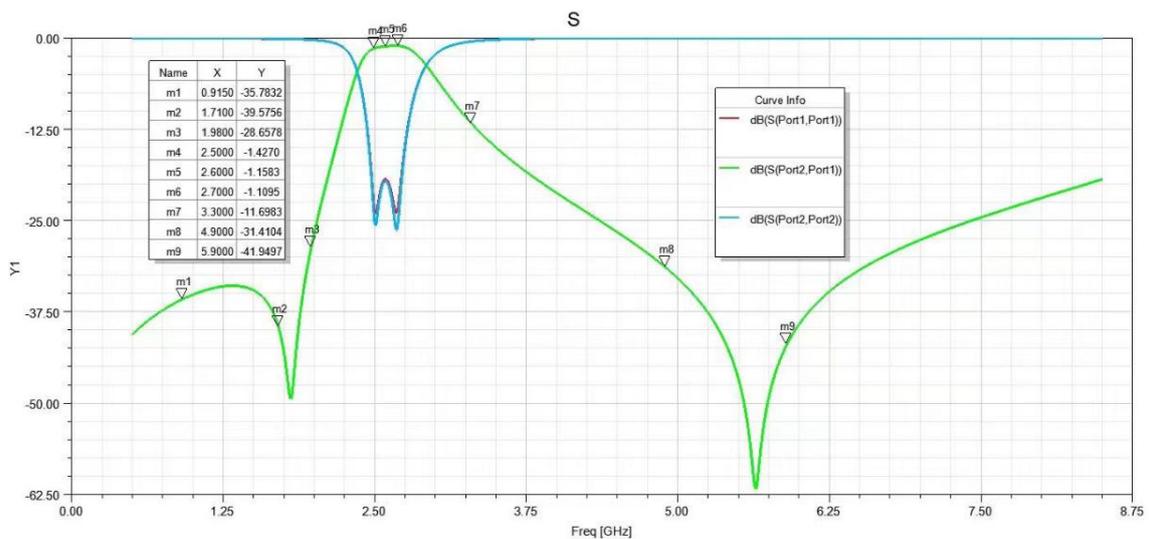
- Land
- ▨ Solder
- Through-hole

Unit: mm
Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	1.60±0.15
	W	0.80±0.15
	T	0.60±0.15
	A	0.30±0.10
	B	0.20±0.10
	C	0.7±0.10
	D	0.2±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.